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### Details

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Product Status	Active
Core Processor	HCS12X
Core Size	16-Bit
Speed	80MHz
Connectivity	CANbus, I <sup>2</sup> C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	91
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.5V
Data Converters	A/D 8x10b, 16x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	112-LQFP
Supplier Device Package	112-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=s912xdp512j1mal

Email: info@E-XFL.COM

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Chapter 2 Clocks and Reset Generator (S12CRGV6)

# 2.1.3 Block Diagram

Figure 2-1 shows a block diagram of the CRG.



Figure 2-1. CRG Block Diagram



# 2.3.2.1 CRG Synthesizer Register (SYNR)

The SYNR register controls the multiplication factor of the PLL. If the PLL is on, the count in the loop divider (SYNR) register effectively multiplies up the PLL clock (PLLCLK) from the reference frequency by 2 x (SYNR + 1). PLLCLK will not be below the minimum VCO frequency ( $f_{SCM}$ ).

 $PLLCLK = 2xOSCCLKx \frac{(SYNR + 1)}{(REFDV + 1)}$ 

### NOTE

If PLL is selected (PLLSEL=1), Bus Clock = PLLCLK / 2 Bus Clock must not exceed the maximum operating system frequency.



Figure 2-4. CRG Synthesizer Register (SYNR)

Read: Anytime

Write: Anytime except if PLLSEL = 1

### NOTE

Write to this register initializes the lock detector bit and the track detector bit.

### 2.3.2.2 CRG Reference Divider Register (REFDV)

The REFDV register provides a finer granularity for the PLL multiplier steps. The count in the reference divider divides OSCCLK frequency by REFDV + 1.



### Figure 2-5. CRG Reference Divider Register (REFDV)

Read: Anytime

Write: Anytime except when PLLSEL = 1

### NOTE

Write to this register initializes the lock detector bit and the track detector bit.



2 Clocks and Reset Generator (S12CRGV6)

# 2.3.2.9 CRG COP Control Register (COPCTL)

This register controls the COP (computer operating properly) watchdog.



1. Refer to Device User Guide (Section: CRG) for reset values of WCOP, CR2, CR1, and CR0. = Unimplemented or Reserved

Figure 2-12. CRG COP Control Register (COPCTL)

### Read: Anytime

Write:

- 1. RSBCK: Anytime in special modes; write to "1" but not to "0" in all other modes
- 2. WCOP, CR2, CR1, CR0:
  - Anytime in special modes

Write once in all other modes
 Writing CR[2:0] to "000" has no effect, but counts for the "write once" condition.
 Writing WCOP to "0" has no effect, but counts for the "write once" condition.

The COP time-out period is restarted if one these two conditions is true:

1. Writing a nonzero value to CR[2:0] (anytime in special modes, once in all other modes) with WRTMASK = 0.

or

2. Changing RSBCK bit from "0" to "1".

### Table 2-9. COPCTL Field Descriptions

Field	Description
7 WCOP	<ul> <li>Window COP Mode Bit — When set, a write to the ARMCOP register must occur in the last 25% of the selected period. A write during the first 75% of the selected period will reset the part. As long as all writes occur during this window, 0x_55 can be written as often as desired. Once 0x_AA is written after the 0x_55, the time-out logic restarts and the user must wait until the next window before writing to ARMCOP. Table 2-10 shows the duration of this window for the seven available COP rates.</li> <li>0 Normal COP operation</li> <li>1 Window COP operation</li> </ul>
6 RSBCK	<ul> <li>COP and RTI Stop in Active BDM Mode Bit</li> <li>0 Allows the COP and RTI to keep running in active BDM mode.</li> <li>1 Stops the COP and RTI counters whenever the part is in active BDM mode.</li> </ul>

Chapter 6 XGATE (S12XGATEV2)



### **Transfer from and to Special Registers**

# TFR

### Operation

TFR RD,CCR: CCR  $\Rightarrow$  RD[3:0]; 0  $\Rightarrow$  RD[15:4] TFR CCR,RD: RD[3:0]  $\Rightarrow$  CCR TFR RD,PC: PC+4  $\Rightarrow$  RD

Transfers the content of one RISC core register to another. The TFR RD,PC instruction can be used to implement relative subroutine calls.

### Example:

	TFR BRA	R7, PC SUBR	;Return address (RETADDR) is stored in R7 ;Relative branch to subroutine (SUBR)
RETADDR	• • •		
SUBR	JAL	R7	;Jump to return address (RETADDR)

### **CCR Effects**

TFR RD,CCR, TFR RD,PC:

Ν	Ζ	V	С
—			

- N: Not affected.
- Z: Not affected.
- V: Not affected.
- C: Not affected.

# NZVC $\Delta$ $\Delta$ $\Delta$ $\Delta$ N:RS[3].Z:RS[2].V:RS[1].

TFR CCR,RS:

C: RS[0].

### **Code and CPU Cycles**

Source Form	Address Mode	Machine Code									Cycles					
TFR RD,CCR CCR $\Rightarrow$ RD	MON	0	0	0	0	0	RD	1	1	1	1	1	0	0	0	Р
TFR CCR,RS RS $\Rightarrow$ CCR	MON	0	0	0	0	0	RS	1	1	1	1	1	0	0	1	Р
TFR RD,PCPC+4 $\Rightarrow$ RD	MON	0	0	0	0	0	RD	1	1	1	1	1	0	1	0	Р



XGATE (S12XGATEV2)	
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Functionality	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ANDH RD, #IMM8	1	0	0	0	1	<b></b>	RD					IMI	M8			
BITL RD, #IMM8	1	0	0	1	0		RD					IMI	8N			
BITH RD, #IMM8	1	0	0	1	1		RD					IMI	M8			
ORL RD, #IMM8	1	0	1	0	0		RD					IMI	M8			
ORH RD, #IMM8	1	0	1	0	1		RD					IMI	M8			
XNORL RD, #IMM8	1	0	1	1	0		RD					IMI	M8			
XNORH RD, #IMM8	1	0	1	1	1		RD		IMM8							
Arithmetic Immediate Instructions																
SUBL RD, #IMM8	1	1	0	0	0		RD					IMI	M8			
SUBH RD, #IMM8	1	1	0	0	1		RD					IMI	M8			
CMPL RS, #IMM8	1	1	0	1	0		RS					IMI	M8			
CPCH RS, #IMM8	1	1	0	1	1		RS					IMI	M8			
ADDL RD, #IMM8	1	1	1	0	0	RD IMM8		M8								
ADDH RD, #IMM8	1	1	1	0	1	RD IMM8										
LDL RD, #IMM8	1	1	1	1	0	RD		RD			IMM8					
LDH RD, #IMM8	1	1	1	1	1		RD					IMI	8N			

### Table 6-17. Instruction Set Summary (Sheet 3 of 3)





# 7.3.2.23 Input Control Overwrite Register (ICOVW)



Read: Anytime

Write: Anytime

All bits reset to zero.

### Table 7-29. ICOVW Field Descriptions

Field	Description
7:0 NOVW[7:0]	<ul> <li>No Input Capture Overwrite</li> <li>The contents of the related capture register or holding register can be overwritten when a new input capture or latch occurs.</li> <li>The related capture register or holding register cannot be written by an event unless they are empty (see Section 7.4.1.1, "IC Channels"). This will prevent the captured value being overwritten until it is read or latched in the holding register.</li> </ul>



### Chapter 10 Freescale's Scalable Controller Area Network (S12MSCANV3)



### Figure 10-42. 8-bit Maskable Identifier Acceptance Filters

	MSCAN Mode										
CPU Mode		Reduced Power Consumption									
	Normal	Sleep	Power Down	Disabled (CANE=0)							
RUN	CSWAI = X <sup>1</sup> SLPRQ = 0 SLPAK = 0	CSWAI = X SLPRQ = 1 SLPAK = 1		CSWAI = X SLPRQ = X SLPAK = X							
WAIT	CSWAI = 0 SLPRQ = 0 SLPAK = 0	CSWAI = 0 SLPRQ = 1 SLPAK = 1	CSWAI = 1 SLPRQ = X SLPAK = X	CSWAI = X SLPRQ = X SLPAK = X							
STOP			CSWAI = X SLPRQ = X SLPAK = X	CSWAI = X SLPRQ = X SLPAK = X							

### Table 10-36. CPU vs. MSCAN Operating Modes

<sup>1</sup> 'X' means don't care.

### 10.4.5.1 Operation in Run Mode

As shown in Table 10-36, only MSCAN sleep mode is available as low power option when the CPU is in run mode.

### 10.4.5.2 Operation in Wait Mode

The WAI instruction puts the MCU in a low power consumption stand-by mode. If the CSWAI bit is set, additional power can be saved in power down mode because the CPU clocks are stopped. After leaving this power down mode, the MSCAN restarts its internal controllers and enters normal mode again.

While the CPU is in wait mode, the MSCAN can be operated in normal mode and generate interrupts (registers can be accessed via background debug mode). The MSCAN can also operate in any of the low-power modes depending on the values of the SLPRQ/SLPAK and CSWAI bits as seen in Table 10-36.

### 10.4.5.3 Operation in Stop Mode

The STOP instruction puts the MCU in a low power consumption stand-by mode. In stop mode, the MSCAN is set in power down mode regardless of the value of the SLPRQ/SLPAK and CSWAI bits (Table 10-36).

### 10.4.5.4 MSCAN Sleep Mode

The CPU can request the MSCAN to enter this low power mode by asserting the SLPRQ bit in the CANCTL0 register. The time when the MSCAN enters sleep mode depends on a fixed synchronization delay and its current activity:



# 11.3.2.7 SCI Status Register 1 (SCISR1)

The SCISR1 and SCISR2 registers provides inputs to the MCU for generation of SCI interrupts. Also, these registers can be polled by the MCU to check the status of these bits. The flag-clearing procedures require that the status register be read followed by a read or write to the SCI data register. It is permissible to execute other instructions between the two steps as long as it does not compromise the handling of I/O, but the order of operations is important for flag clearing.



Figure 11-10. SCI Status Register 1 (SCISR1)

Read: Anytime

Write: Has no meaning or effect

Table 11-10. SCISR1 Field Descriptions	Table	11-10.	SCISR1	Field	Descriptions
--	-------	--------	--------	-------	--------------

Field	Description
7 TDRE	Transmit Data Register Empty Flag — TDRE is set when the transmit shift register receives a byte from the SCI data register. When TDRE is 1, the transmit data register (SCIDRH/L) is empty and can receive a new value to transmit.Clear TDRE by reading SCI status register 1 (SCISR1), with TDRE set and then writing to SCI data register low (SCIDRL).0No byte transferred to transmit shift register 
6 TC	<ul> <li>Transmit Complete Flag — TC is set low when there is a transmission in progress or when a preamble or break character is loaded. TC is set high when the TDRE flag is set and no data, preamble, or break character is being transmitted. When TC is set, the TXD pin becomes idle (logic 1). Clear TC by reading SCI status register 1 (SCISR1) with TC set and then writing to SCI data register low (SCIDRL). TC is cleared automatically when data, preamble, or break is queued and ready to be sent. TC is cleared in the event of a simultaneous set and clear of the TC flag (transmission not complete).</li> <li>0 Transmission in progress</li> <li>1 No transmission in progress</li> </ul>
5 RDRF	<ul> <li>Receive Data Register Full Flag — RDRF is set when the data in the receive shift register transfers to the SCI data register. Clear RDRF by reading SCI status register 1 (SCISR1) with RDRF set and then reading SCI data register low (SCIDRL).</li> <li>0 Data not available in SCI data register</li> <li>1 Received data available in SCI data register</li> </ul>
4 IDLE	<ul> <li>Idle Line Flag — IDLE is set when 10 consecutive logic 1s (if M = 0) or 11 consecutive logic 1s (if M = 1) appear on the receiver input. Once the IDLE flag is cleared, a valid frame must again set the RDRF flag before an idle condition can set the IDLE flag.Clear IDLE by reading SCI status register 1 (SCISR1) with IDLE set and then reading SCI data register low (SCIDRL).</li> <li>0 Receiver input is either active now or has never become active since the IDLE flag was last cleared 1 Receiver input has become idle</li> <li>Note: When the receiver wakeup bit (RWU) is set, an idle line condition does not set the IDLE flag.</li> </ul>

11 Serial Communication Interface (S12SCIV5)

# 11.4.1 Infrared Interface Submodule

This module provides the capability of transmitting narrow pulses to an IR LED and receiving narrow pulses and transforming them to serial bits, which are sent to the SCI. The IrDA physical layer specification defines a half-duplex infrared communication link for exchange data. The full standard includes data rates up to 16 Mbits/s. This design covers only data rates between 2.4 Kbits/s and 115.2 Kbits/s.

The infrared submodule consists of two major blocks: the transmit encoder and the receive decoder. The SCI transmits serial bits of data which are encoded by the infrared submodule to transmit a narrow pulse for every zero bit. No pulse is transmitted for every one bit. When receiving data, the IR pulses should be detected using an IR photo diode and transformed to CMOS levels by the IR receive decoder (external from the MCU). The narrow pulses are then stretched by the infrared submodule to get back to a serial bit stream to be received by the SCI. The polarity of transmitted pulses and expected receive pulses can be inverted so that a direct connection can be made to external IrDA transceiver modules that uses active low pulses.

The infrared submodule receives its clock sources from the SCI. One of these two clocks are selected in the infrared submodule in order to generate either 3/16, 1/16, 1/32 or 1/4 narrow pulses during transmission. The infrared block receives two clock sources from the SCI, R16XCLK and R32XCLK, which are configured to generate the narrow pulse width during transmission. The R16XCLK and R32XCLK are internal clocks with frequencies 16 and 32 times the baud rate respectively. Both R16XCLK and R32XCLK clocks are used for transmitting data. The receive decoder uses only the R16XCLK clock.

# 11.4.1.1 Infrared Transmit Encoder

The infrared transmit encoder converts serial bits of data from transmit shift register to the TXD pin. A narrow pulse is transmitted for a zero bit and no pulse for a one bit. The narrow pulse is sent in the middle of the bit with a duration of 1/32, 1/16, 3/16 or 1/4 of a bit time. A narrow high pulse is transmitted for a zero bit when TXPOL is cleared, while a narrow low pulse is transmitted for a zero bit when TXPOL is set.

# 11.4.1.2 Infrared Receive Decoder

The infrared receive block converts data from the RXD pin to the receive shift register. A narrow pulse is expected for each zero received and no pulse is expected for each one received. A narrow high pulse is expected for a zero bit when RXPOL is cleared, while a narrow low pulse is expected for a zero bit when RXPOL is set. This receive decoder meets the edge jitter requirement as defined by the IrDA serial infrared physical layer specification.

# 11.4.2 LIN Support

This module provides some basic support for the LIN protocol. At first this is a break detect circuitry making it easier for the LIN software to distinguish a break character from an incoming data stream. As a further addition is supports a collision detection at the bit level as well as cancelling pending transmissions.

### Chapter 11 Serial Communication Interface (S12SCIV5)



## 11.4.5.5 LIN Transmit Collision Detection

This module allows to check for collisions on the LIN bus.



Figure 11-18. Collision Detect Principle

If the bit error circuit is enabled (BERRM[1:0] = 0:1 or = 1:0]), the error detect circuit will compare the transmitted and the received data stream at a point in time and flag any mismatch. The timing checks run when transmitter is active (not idle). As soon as a mismatch between the transmitted data and the received data is detected the following happens:

- The next bit transmitted will have a high level (TXPOL = 0) or low level (TXPOL = 1)
- The transmission is aborted and the byte in transmit buffer is discarded.
- the transmit data register empty and the transmission complete flag will be set
- The bit error interrupt flag, BERRIF, will be set.
- No further transmissions will take place until the BERRIF is cleared.



Figure 11-19. Timing Diagram Bit Error Detection

If the bit error detect feature is disabled, the bit error interrupt flag is cleared.

### NOTE

The RXPOL and TXPOL bit should be set the same when transmission collision detect feature is enabled, otherwise the bit error interrupt flag may be set incorrectly.



indicating that the received byte can be read. If the receive interrupt enable bit, RIE, in SCI control register 2 (SCICR2) is also set, the RDRF flag generates an RDRF interrupt request.

# 11.4.6.3 Data Sampling

The RT clock rate. The RT clock is an internal signal with a frequency 16 times the baud rate. To adjust for baud rate mismatch, the RT clock (see Figure 11-21) is re-synchronized:

- After every start bit
- After the receiver detects a data bit change from logic 1 to logic 0 (after the majority of data bit samples at RT8, RT9, and RT10 returns a valid logic 1 and the majority of the next RT8, RT9, and RT10 samples returns a valid logic 0)

To locate the start bit, data recovery logic does an asynchronous search for a logic 0 preceded by three logic 1s. When the falling edge of a possible start bit occurs, the RT clock begins to count to 16.



### Figure 11-21. Receiver Data Sampling

To verify the start bit and to detect noise, data recovery logic takes samples at RT3, RT5, and RT7. Figure 11-16 summarizes the results of the start bit verification samples.

RT3, RT5, and RT7 Samples	Start Bit Verification	Noise Flag
000	Yes	0
001	Yes	1
010	Yes	1
011	No	0
100	Yes	1
101	No	0
110	No	0
111	No	0

Table 11-16. Start Bit Verification

If start bit verification is not successful, the RT clock is reset and a new search for a start bit begins.

14 Voltage Regulator (S12VREG3V3V5)

### 14.3.2.5 Autonomous Periodical Interrupt Rate High and Low Register (VREGAPIRH / VREGAPIRL)

The VREGAPIRH and VREGAPIRL register allows the configuration of the VREG\_3V3 autonomous periodical interrupt rate.



Figure 14-7. Autonomous Periodical Interrupt Rate Low Register (VREGAPIRL)

### Table 14-7. VREGAPIRH / VREGAPIRL Field Descriptions

Field	Description
11-0 APIR[11:0]	<b>Autonomous Periodical Interrupt Rate Bits</b> — These bits define the timeout period of the API. See Table 14-8 for details of the effect of the autonomous periodical interrupt rate bits. Writable only if APIFE = 0 of VREGAPICL register.





# 21.5.2.2 Example 2b: Emulation Expanded Mode

This mode is used for emulation systems in which the target application is operating in normal expanded mode.

If the external bus is used with a PRU, the external device rebuilds the data select and data direction signals  $\overline{\text{UDS}}$ ,  $\overline{\text{LDS}}$ ,  $\overline{\text{RE}}$ , and  $\overline{\text{WE}}$  from the ADDR0,  $\overline{\text{LSTRB}}$ , and  $R/\overline{\text{W}}$  signals.

Figure 21-6 shows the PRU connection with the available external bus signals in an emulator application.



Figure 21-6. Application in Emulation Expanded Mode

The timings of accesses with 1 stretch cycle are shown in

- Figure 'Example 2b: Emulation Expanded Mode Read with 1 Stretch Cycle'
- Figure 'Example 2b: Emulation Expanded Mode Write with 1 Stretch Cycle'

The associated timing numbers are given in

• Table 'Example 2b: Emulation Expanded Mode Timing  $V_{DD5} = 5.0 \text{ V}$  (EWAITE = 0)' (this also includes examples for alternative settings of 2 and 3 additional stretch cycles)

Timing considerations:

• If no stretch cycle is added, the timing is the same as in Emulation Single-Chip Mode.



### Table 23-16. ECLKCTL Field Descriptions (continued)

Field	Description
6 NCLKX2	No ECLKX2 — This bit controls the availability of a free-running clock on the ECLKX2 pin. This clock has a fixed rate of twice the internal bus clock. Clock output is always active in emulation modes and if enabled in all other operating modes. 0 ECLKX2 is enabled 1 ECLKX2 is disabled
1–0 EDIV[1:0]	<b>Free-Running ECLK Divider</b> — These bits determine the rate of the free-running clock on the ECLK pin. The usage of the bits is shown in Table 23-17. Divider is always disabled in emulation modes and active as programmed in all other operating modes.

### Table 23-17. Free-Running ECLK Clock Rate

EDIV[1:0]	Rate of Free-Running ECLK
00	ECLK = Bus clock rate
01	ECLK = Bus clock rate divided by 2
10	ECLK = Bus clock rate divided by 3
11	ECLK = Bus clock rate divided by 4

# 23.0.5.14 IRQ Control Register (IRQCR)



# Figure 23-16. IRQ Control Register (IRQCR)

Read: See individual bit descriptions below.

Write: See individual bit descriptions below.

### Table 23-18. IRQCR Field Descriptions

Field	Description				
7 IRQE	<ul> <li>IRQ Select Edge Sensitive Only</li> <li>Special modes: Read or write anytime.</li> <li>Normal and emulation modes: Read anytime, write once.</li> <li>IRQ configured for low level recognition.</li> <li>IRQ configured to respond only to falling edges. Falling edges on the IRQ pin will be detected anytime IRQE = 1 and will be cleared only upon a reset or the servicing of the IRQ interrupt.</li> </ul>				
6 IRQEN	External IRQ EnableRead or write anytime.0 External IRQ pin is disconnected from interrupt logic.1 External IRQ pin is connected to interrupt logic.				

### 26 4 Kbyte EEPROM Module (S12XEETX4KV2)

All EDHI and EDLO bits are readable and writable in special modes.

# 26.4 Functional Description

# 26.4.1 EEPROM Command Operations

Write operations are used to execute program, erase, erase verify, sector erase abort, and sector modify algorithms described in this section. The program, erase, and sector modify algorithms are controlled by a state machine whose timebase, EECLK, is derived from the oscillator clock via a programmable divider. The command register as well as the associated address and data registers operate as a buffer and a register (2-stage FIFO) so that a second command along with the necessary data and address can be stored to the buffer while the first command is still in progress. Buffer empty as well as command completion are signalled by flags in the EEPROM status register with interrupts generated, if enabled.

The next sections describe:

- 1. How to write the ECLKDIV register
- 2. Command write sequences to program, erase, erase verify, sector erase abort, and sector modify operations on the EEPROM memory
- 3. Valid EEPROM commands
- 4. Effects resulting from illegal EEPROM command write sequences or aborting EEPROM operations

# 26.4.1.1 Writing the ECLKDIV Register

Prior to issuing any EEPROM command after a reset, the user is required to write the ECLKDIV register to divide the oscillator clock down to within the 150 kHz to 200 kHz range. Since the program and erase timings are also a function of the bus clock, the ECLKDIV determination must take this information into account.

If we define:

- ECLK as the clock of the EEPROM timing control block
- Tbus as the period of the bus clock
- INT(x) as taking the integer part of x (e.g., INT(4.323)=4)

then ECLKDIV register bits PRDIV8 and EDIV[5:0] are to be set as described in Figure 26-17.

For example, if the oscillator clock frequency is 950 kHz and the bus clock frequency is 10 MHz, ECLKDIV bits EDIV[5:0] should be set to 0x04 (000100) and bit PRDIV8 set to 0. The resulting EECLK frequency is then 190 kHz. As a result, the EEPROM program and erase algorithm timings are increased over the optimum target by:

$$(200 - 190)/200 \times 100 = 5\%$$

If the oscillator clock frequency is 16 MHz and the bus clock frequency is 40 MHz, ECLKDIV bits EDIV[5:0] should be set to 0x0A (001010) and bit PRDIV8 set to 1. The resulting EECLK frequency is







# A.1.9 I/O Characteristics

This section describes the characteristics of all I/O pins except EXTAL, XTAL, XFC, TEST, VREGEN and supply pins.

### CAUTION

The internal pull up/pull down device specification is different depending on maskset.

Conditions are 3.15 V < $V_{DD35}$ < 3.6 V temperature from –40°C to +140°C, unless otherwise noted I/O Characteristics for all I/O pins except EXTAL, XTAL,XFC,TEST, VREGEN and supply pins.							
Num	С	Rating	Symbol	Min	Тур	Max	Unit
1	Ρ	Input high voltage	V <sub>IH</sub>	0.65*V <sub>DD35</sub>	_	—	V
	Т	Input high voltage	V <sub>IH</sub>	—	—	V <sub>DD35</sub> + 0.3	V
2	Ρ	Input low voltage	V <sub>IL</sub>	—	—	0.35*V <sub>DD35</sub>	V
	Т	Input low voltage	V <sub>IL</sub>	$V_{SS35} - 0.3$	—	—	V
3	С	Input hysteresis	V <sub>HYS</sub>	250			mV
4	С	Input leakage current (pins in high impedance input mode) <sup>1</sup> Vin = V <sub>DD35</sub> or V <sub>SS35</sub>	l <sub>.</sub> in	-1	—	1	μA
5	С	Output high voltage (pins in output mode) Partial drive $I_{OH} = -0.75$ mA	V <sub>OH</sub>	V <sub>DD35</sub> – 0.4 —		—	V
6	Р	Output high voltage (pins in output mode) Full drive I <sub>OH</sub> = -4 mA	V <sub>OH</sub>	V <sub>DD35</sub> - 0.4 —		—	V
7	С	Output low voltage (pins in output mode) Partial Drive I <sub>OL</sub> = +0.9 mA	V <sub>OL</sub>			0.4	V
8	Ρ	Output low voltage (pins in output mode) Full Drive I <sub>OL</sub> = +4.75 mA	V <sub>OL</sub>	—	—	0.4	V
Internal pull up/pull down device specification (items 9 to 12) only valid for masksets 0L15Y & 1L15Y							
9	Ρ	Internal pull up device current, tested at $V_{IL}$ max.	I <sub>PUL</sub>	—	_	-60	μA
10	С	Internal pull up device current, tested at $V_{IH}$ min.	I <sub>PUH</sub>	-6	_	-	μA
11	Ρ	Internal pull down device current, tested at $\mathrm{V}_{\mathrm{IH}}\mathrm{min}.$	I <sub>PDH</sub>	—		60	μA
12	С	Internal pull down device current, tested at $V_{IL}$ max.	I <sub>PDL</sub>	6		—	μA
		Internal pull up/pull down device specification	(items 13 to	o 14) valid for	all other ma	asksets	
13	Ρ	Internal pull up resistance VIH min > input voltage > VIL max	R <sub>PUL</sub>	25		55	KΩ
14	Ρ	Internal pull down resistance VIH min > input voltage > VIL max	R <sub>PDH</sub>	25		55	KΩ
15	D	Input capacitance	C <sub>in</sub>	—	6	—	pF
16	Т	Injection current <sup>2</sup> Single pin limit Total device limit, sum of all injected currents	I <sub>ICS</sub> I <sub>ICP</sub>	2.5 25	_	2.5 25	mA

### Table A-6. 3.3-V I/O Characteristics





# A.5 Reset, Oscillator, and PLL

This section summarizes the electrical characteristics of the various startup scenarios for oscillator and phase-locked loop (PLL).

# A.5.1 Startup

Table A-21 summarizes several startup characteristics explained in this section. Detailed description of the startup behavior can be found in the Clock and Reset Generator (CRG) Block Guide.

Conditions are shown in Table A-4unless otherwise noted							
Num	С	Rating	Symbol	Min	Тур	Max	Unit
1	D	Reset input pulse width, minimum input time	PW <sub>RSTL</sub>	2	—	—	t <sub>osc</sub>
2	D	Startup from reset	n <sub>RST</sub>	192	—	196	n <sub>osc</sub>
3	D	Interrupt pulse width, IRQ edge-sensitive mode	PWIRQ	25 <sup>1</sup>	—	—	ns
4	D	Wait recovery startup time	t <sub>WRS</sub>	—	—	14	t <sub>cyc</sub>
5	D	Fast wakeup from STOP <sup>2</sup>	t <sub>fws</sub>	—	50	—	μs

Table A-21. Startup Characteristics

<sup>1</sup> 1 t<sub>cycle</sub> at 40Mhz Bus Clock

 $^{2}$  V<sub>DD1</sub>/V<sub>DD2</sub> filter capacitors 220 nF, V<sub>DD35</sub> = 5 V, T= 25°C

# A.5.1.1 POR

The release level  $V_{PORR}$  and the assert level  $V_{PORA}$  are derived from the  $V_{DD}$  supply. They are also valid if the device is powered externally. After releasing the POR reset the oscillator and the clock quality check are started. If after a time  $t_{CQOUT}$  no valid oscillation is detected, the MCU will start using the internal self clock. The fastest startup time possible is given by  $n_{uposc}$ .

# A.5.1.2 SRAM Data Retention

Provided an appropriate external reset signal is applied to the MCU, preventing the CPU from executing code when  $V_{DD35}$  is out of specification limits, the SRAM contents integrity is guaranteed if after the reset the PORF bit in the CRG flags register has not been set.

# A.5.1.3 External Reset

When external reset is asserted for a time greater than  $PW_{RSTL}$  the CRG module generates an internal reset, and the CPU starts fetching the reset vector without doing a clock quality check, if there was an oscillation before reset.

# A.5.1.4 Stop Recovery

Out of stop the controller can be woken up by an external interrupt. A clock quality check as after POR is performed before releasing the clocks to the system.